

RJK5020DPK

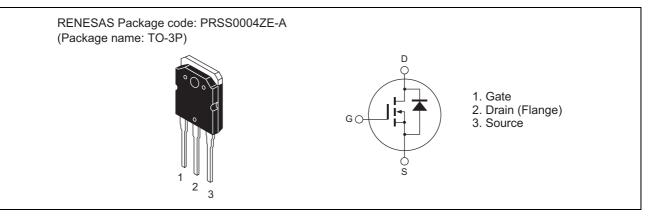
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G1263-0100 Rev.1.00 Sep. 23, 2005

Features

- Low on-resistance
- Low leakage current
- High speed switching

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	500	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	Ι _D	40	А
Drain peak current	Note1 I _{D (pulse)}	120	А
Body-drain diode reverse drain current	I _{DR}	40	А
Body-drain diode reverse drain peak current	Note1 I _{DR (pulse)}	120	А
Avalanche current	I _{AP} ^{Note3}	12.5	А
Avalanche energy	E _{AR} ^{Note3}	8.6	mJ
Channel dissipation	Pch Note2	200	W
Channel to case thermal impedance	θch-c	0.625	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at Tc = 25°C

3. STch = 25° C, Tch $\leq 150^{\circ}$ C



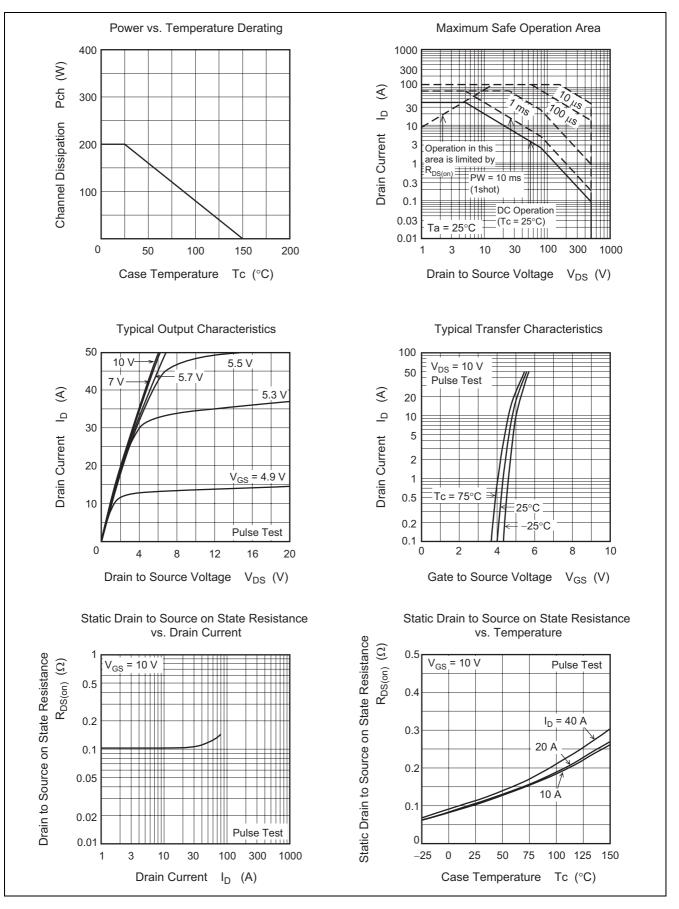
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	500	—		V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}		—	1	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30$ V, $V_{DS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS(on)}	_	0.102	0.115	Ω	$I_D = 20 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
Input capacitance	Ciss	_	5150		pF	V _{DS} = 25 V
Output capacitance	Coss	_	525		pF	V _{GS} = 0 f = 1 MHz
Reverse transfer capacitance	Crss	_	55		pF	
Turn-on delay time	t _{d(on)}	_	52		ns	I _D = 20 A
Rise time	tr	_	115		ns	$V_{GS} = 10 V$ $R_L = 12.5 \Omega$ $Rg = 10 \Omega$
Turn-off delay time	t _{d(off)}	_	180		ns	
Fall time	t _f	_	125		ns	
Total gate charge	Qg	_	126		nC	V _{DD} = 400 V
Gate to source charge	Qgs	_	26		nC	V _{GS} = 10 V I _D = 40 A
Gate to drain charge	Qgd	_	54		nC	
Body-drain diode forward voltage	V _{DF}	_	0.90	1.50	V	$I_F = 40 \text{ A}, V_{GS} = 0^{Note4}$
Body-drain diode reverse recovery time	t _{rr}		450	—	ns	$I_F = 40 \text{ A}, V_{GS} = 0$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

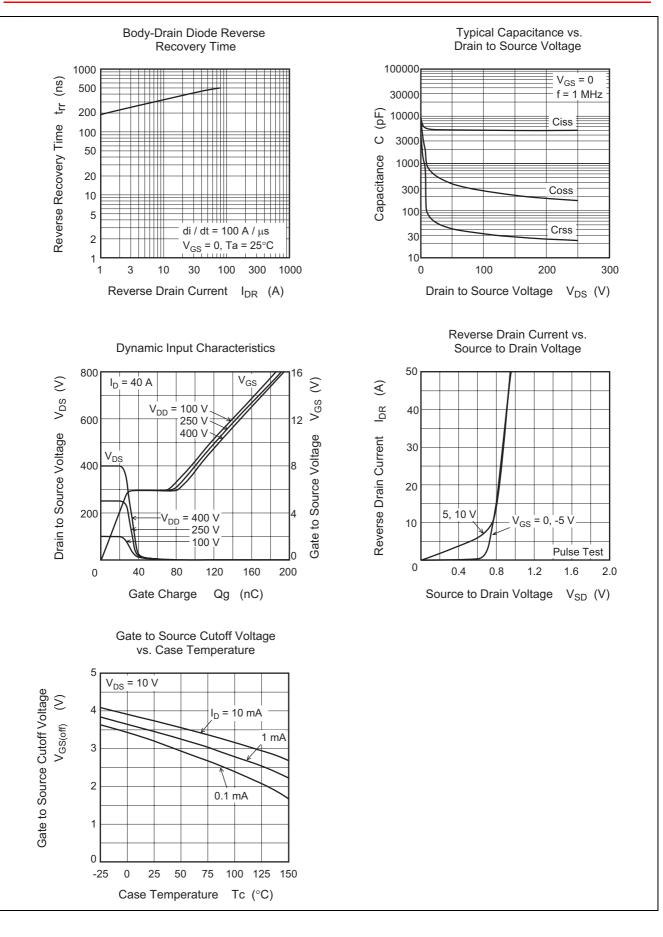
Notes: 4. Pulse test



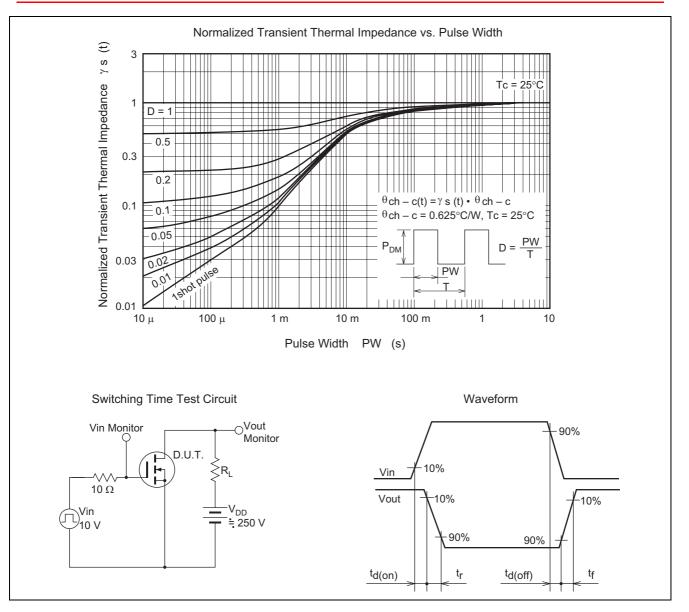
Main Characteristics





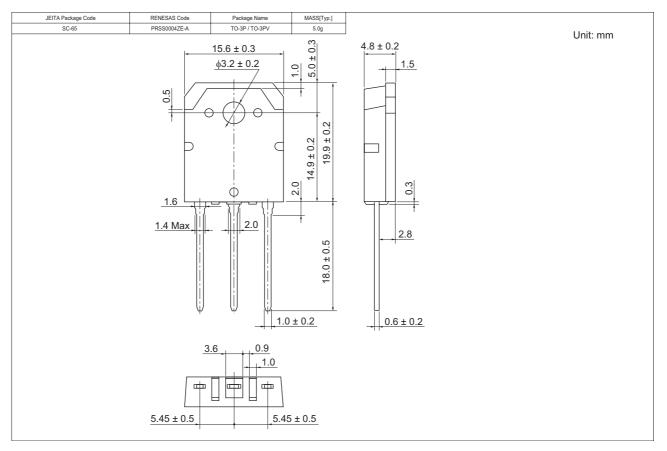








Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
RJK5020DPK-E	30 pcs	Plastic magazine

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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